

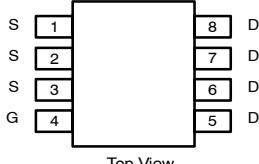
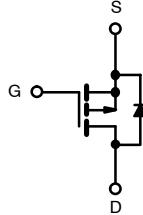


SHENZHEN TUOFENG SEMICONDUCTOR TECHNOLOGY CO.,LTD

# SOP-8 Plastic-Encapsulate MOSFETS

**9435**

P-Channel Enhancement Mode Power MOSFET

<p><b>Description</b> The 9435 uses advanced trench technology to provide excellent <math>R_{DS(ON)}</math>, low gate charge and operation with gate voltages as low as 4.5V.</p> <p><b>General Features</b></p> <ul style="list-style-type: none"><li>● <math>V_{DS} = -30V</math></li><li>● <math>R_{DS(ON)} &lt; 85m\Omega @ V_{GS}=-4.5V \quad I_D = -4.2A</math></li><li>● <math>R_{DS(ON)} &lt; 57m\Omega @ V_{GS}=-10V \quad I_D = -5.3A</math></li><li>● High power and current handing capability</li><li>● Lead free product is acquired</li><li>● Surface mount package</li></ul> <p><b>Application</b></p> <ul style="list-style-type: none"><li>● Battery Switch</li><li>● Load switch</li><li>● Power management</li></ul>	<p><b>SOP-8</b></p>  <p>Top View</p> <p><b>Equivalent Circuit</b></p>  <p><b>MARKING</b></p>  <p>Y :year code W :week code</p>
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## Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current ( $T_J = 150^\circ C$ )	$I_D$	-5.3	A
Drain Current-Pulsed <sup>(Note 1)</sup>	$I_{DM}$	-20	A
Maximum Power Dissipation	$P_D$	2.0	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

## Thermal Characteristic

Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup>	$R_{\theta JA}$	50	°C/W
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**Electrical Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

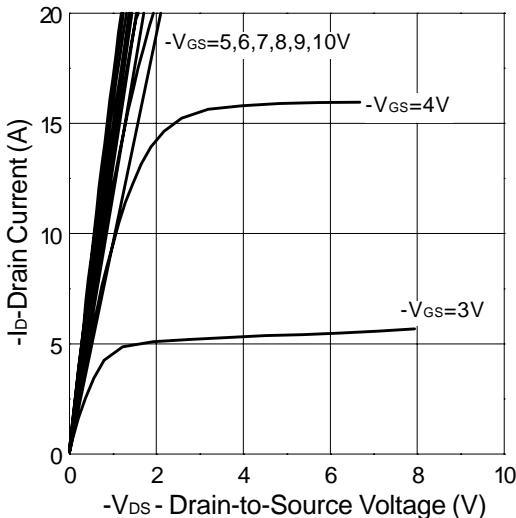
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_{\text{D}}=-250\mu\text{A}$	-30	-33	-	V
Zero Gate Voltage Drain Current	$\text{I}_{\text{DSS}}$	$\text{V}_{\text{DS}}=-24\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	-1	$\mu\text{A}$
Gate-Body Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{GS}}=\pm20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_{\text{D}}=-250\mu\text{A}$	-1	-	-3.0	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=-10\text{V}, \text{I}_{\text{D}}=-5.3\text{A}$	-	51	57	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=-4.5\text{V}, \text{I}_{\text{D}}=-4.2\text{A}$	-	75	85	$\text{m}\Omega$
Forward Transconductance	$\text{g}_{\text{FS}}$	$\text{V}_{\text{DS}}=-15\text{V}, \text{I}_{\text{D}}=-5.3\text{A}$	10	-	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{DS}}=-15\text{V}, \text{V}_{\text{GS}}=0\text{V},$ $F=1.0\text{MHz}$	-	845	-	PF
Output Capacitance	$\text{C}_{\text{oss}}$		-	120	-	PF
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$		-	80	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$\text{V}_{\text{DD}}=-25\text{V}, \text{ID}=-2\text{A},$ $\text{V}_{\text{GS}}=-10\text{V}, \text{R}_{\text{GEN}}=6\Omega$ $\text{R}_{\text{L}}=12.5\Omega$	-	17	-	nS
Turn-on Rise Time	$t_r$		-	18	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	60	-	nS
Turn-Off Fall Time	$t_f$		-	27	-	nS
Total Gate Charge	$\text{Q}_g$	$\text{V}_{\text{DS}}=-15\text{V}, \text{I}_{\text{D}}=-4.6\text{A}$ $\text{V}_{\text{GS}}=-10\text{V}$	-	22	-	nC
Gate-Source Charge	$\text{Q}_{\text{gs}}$		-	4.5	-	nC
Gate-Drain Charge	$\text{Q}_{\text{gd}}$		-	2	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	$\text{V}_{\text{SD}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_{\text{S}}=-2.0\text{A}$	-	-	-1.2	V

**Notes:**

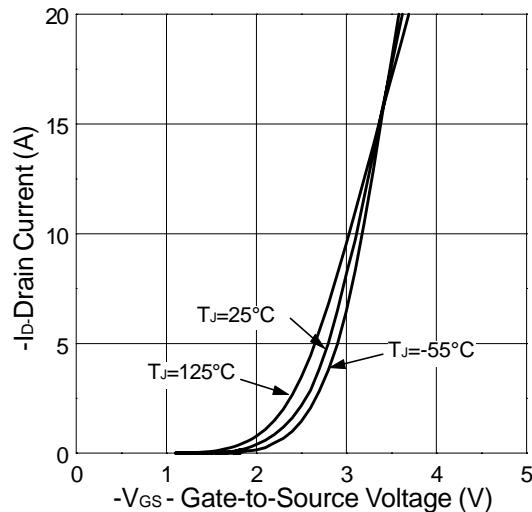
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

## Typical Characteristics

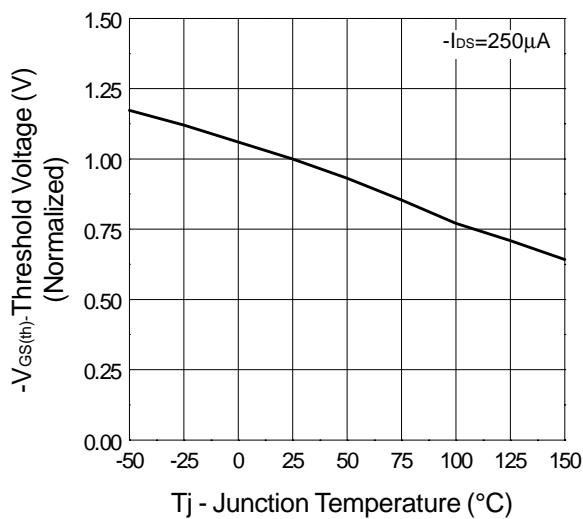
Output Characteristics



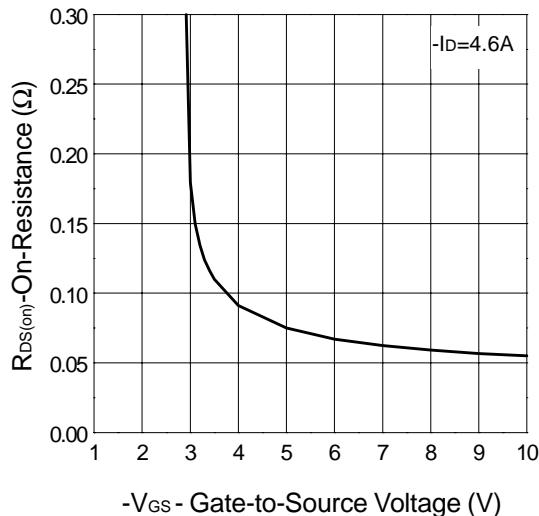
Transfer Characteristics



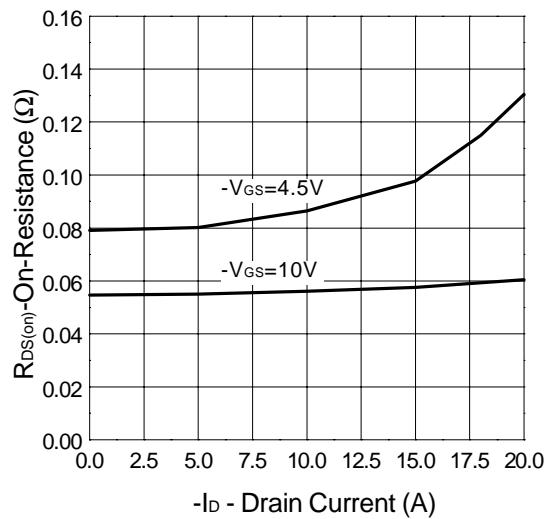
Threshold Voltage vs. Junction Temperature



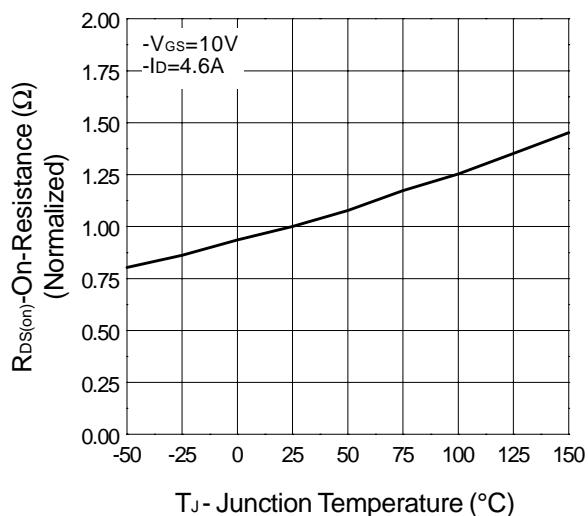
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Drain Current

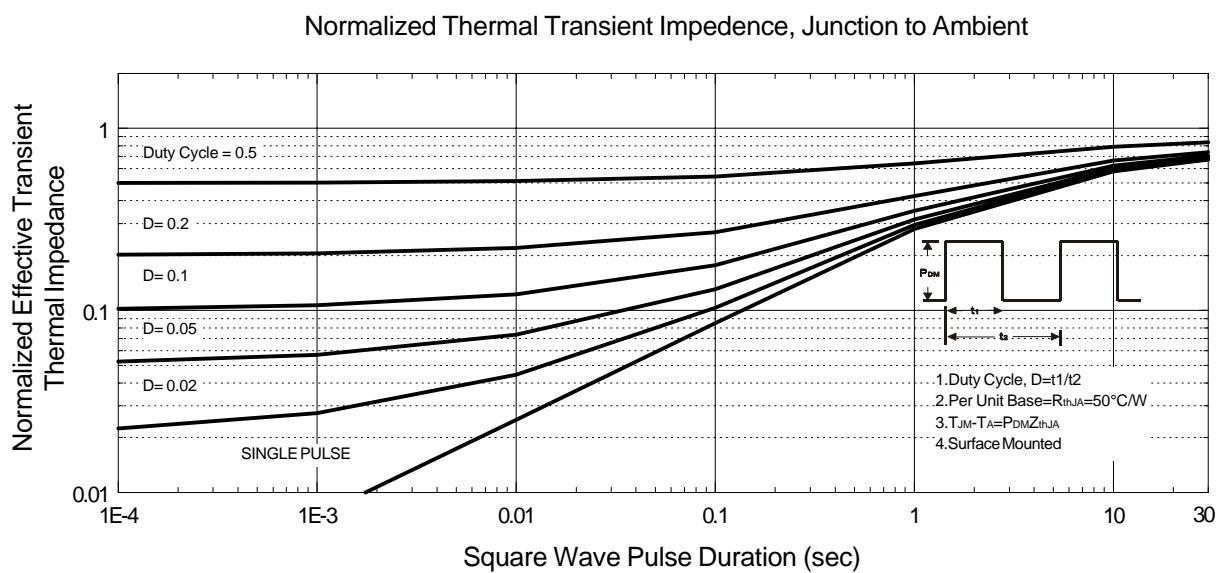
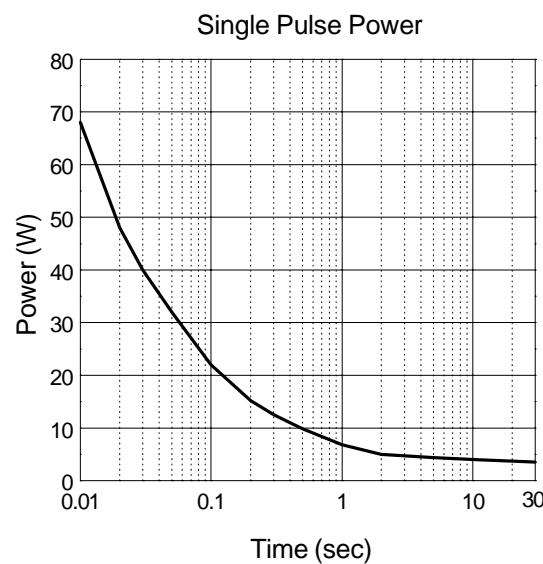
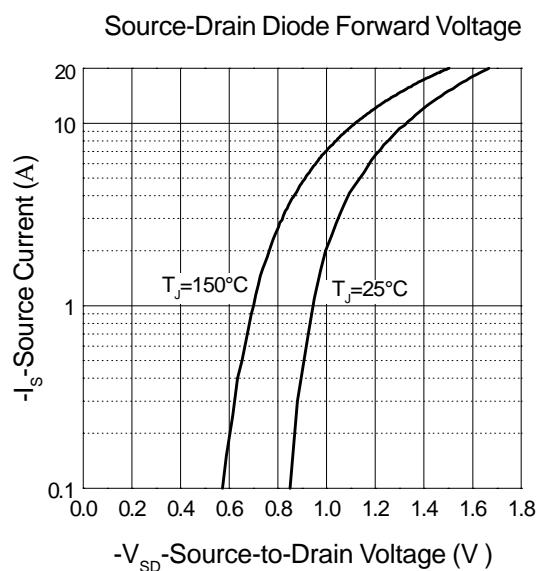
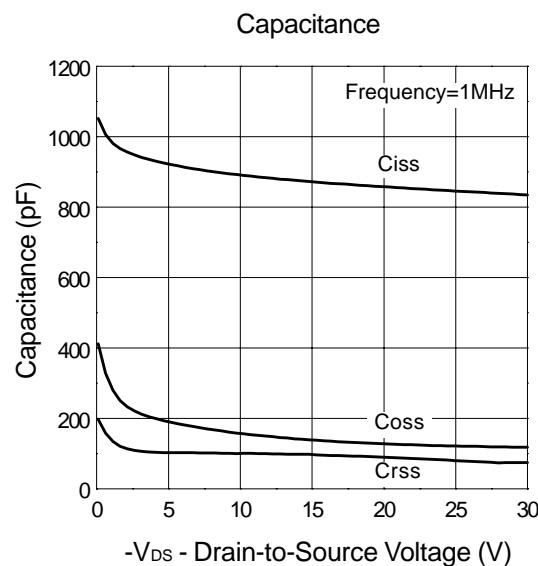
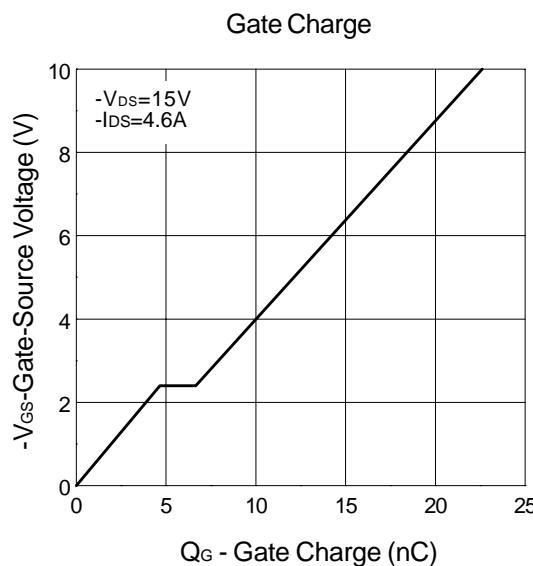


On-Resistance vs. Junction Temperature



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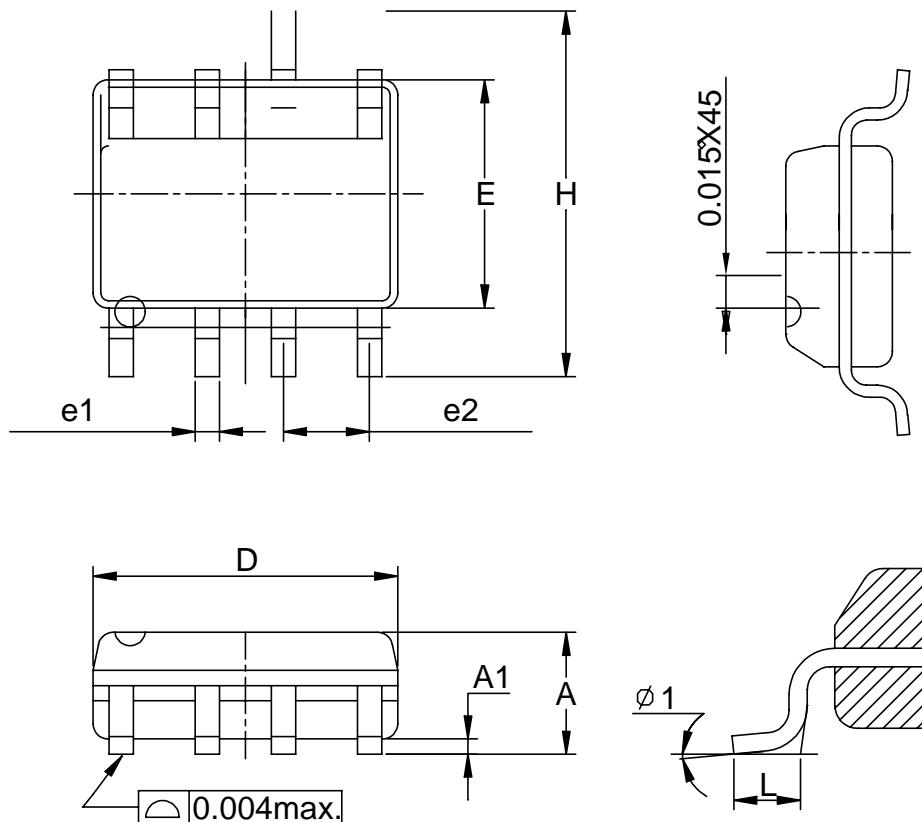
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## Packaging Information

SOP-8 pin ( Reference JEDEC Registration MS-012)



Dim	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
D	4.80	5.00	0.189	0.197
E	3.80	4.00	0.150	0.157
H	5.80	6.20	0.228	0.244
L	0.40	1.27	0.016	0.050
e1	0.33	0.51	0.013	0.020
e2	1.27BSC		0.50BSC	
Ø 1	8°		8°	